ABSTRACT OF THE DISCLOSURE

The invention relates to a method for making microcomponents which exhibit microreliefs, in a substrate (62), consisting of:

- a first step for making the desired microrelief (70, 72, 74) by mechanically machining the substrate and
 - simultaneously with the first step, or after the latter, a second step for cutting out the microcomponents in the substrate.

10 Fig. 5B

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